DTIP 2019

Design, Test, Integration & Packaging of MEMS/MOEMS

Paris - France, May 12th - May 15th, 2019 http://dtip-mems.org

Final Call for Papers

General Chair
Pascal Nouet, U. Montpellier

Local co-Chairs
Jérôme Juillard, CentraleSupélec
Elie Lefeuvre, U. Paris-Sud XI

Publication Chair
Frédérick Mailly, U. Montpellier

CAD, Design and Test Conference

CAD: Integrated CAD/CAE tools, languages and interchange of data, MEMS/MOEMS libraries and IP, Modelling and simulation of fabrication processes, Structured design methodologies, System-level design methodologies

DESIGN: Mechanical simulation, Model order reduction, Multi-physics & Multi-domain simulations, Numerical simulation, other design issues, Signal processing & Front-ends, Thermal evaluation

TEST: Failure mechanisms, Fault modelling, Fault simulation and test pattern generation, Yield estimation

DEVICES & COMPONENTS: RF MEMS, MOEMS, energy harvesting, bio and fluidics, Inertial and Resonant sensors, other sensors & actuators

Micro-fabrication, Integration and Packaging Conference

MICROFABRICATION: assembly technologies, microlithography issues for MEMS/MOEMS, micromachining, micro-molding, nano-imprint, embossing, others

INTEGRATION: flexible technologies and printed electronics, co-integration between MEMS and electronics, 3D technologies

PACKAGING: MOEMS, RF and microwave, vacuum and other harsh environments, others

MATERIALS: piezoelectric, PDMS, others

CHARACTERIZATION: dimensional measurements, non-destructive evaluation, PCM & test structures, physical measurements, reliability and failure analysis

DEVICES & COMPONENTS: RF MEMS, MOEMS, energy harvesting, bio and fluidics, Inertial and Resonant sensors, other sensors & actuators

CONFERENCES

CAD, DESIGN AND TEST	MICROFABRICATION, INTEGRATION AND PACKAGING
Chair: **Peter Schneider**, Fraunhofer IIS/EAS, Dresden, Germany *Co-Chair:* **Francis Pressecq**, CNES, France	*Chair:* **Stewart Smith**, Univ. of Edinburgh, Scotland *Co-Chair:* **Yoshio Mita**, The University of Tokyo, Japan

INVITATION TO PARTICIPATE

DTIP'2019 will be the 20th anniversary edition of the Symposium on Design, Test, Integration & Packaging of MEMS and MOEMS. This unique event brings together participants interested in MEMS/MOEMS processing and those interested in design tools and methods to facilitate the design of MEMS/MOEMS. All aspects including design, modeling, testing, micro-machining, integration and packaging of structures, devices and systems are addressed in two main Conferences, Special Sessions and Invited Talks. Papers presented at the conference will appear in IEEE Xplore and extended version of the presented papers may be submitted for inclusion in a special issue of an indexed journal.

We look forward to welcoming you in Paris next Spring.
Jérôme Juillard, Elie Lefeuvre & Pascal Nouet

It's time to prepare your scientific contributions!

Research paper submission

DTIP aims to present the latest research in "Design, Integration, Test and Packaging of MEMS and MOEMS". A program committee composed with international experts in their field will review all submitted papers. Even if abstracts of about 600 words will be considered, **it is highly recommended to submit extended abstracts (up to 1500 words) plus one page of figures** for efficient and fair scientific reviewing. Detailed instructions regarding electronic submissions are posted on the DTIP website.
Note: Companies that want to advertise their products are discouraged to submit a research paper if there is no revelation of any scientific contribution or rupture with respect to the state-of-the-art. In that later case, it is recommended to consider becoming a sponsor/exhibitor of the conference.

Special sessions

For those of you, who intend to propose a special session, feel free to propose a topic by email (dtip@dtip-mems.org) at your earliest convenience. When proposing a special session, please mention how many submissions are expected. Special session organizers will be in charge of attracting papers, organizing the review and making the final selection with the support of the DTIP organization. The coupling of a special session with an invited talk is strongly recommended.

Invited talks and panels

The symposium program will include three plenary sessions with invited talks and/or technical panels. Feel free to propose topics to be addressed and/or to nominate colleagues for an invited talk.

Venue and important dates

The 2019's edition of DTIP will be held in downtown Paris, France, from May 12th till May 15th. Important dates are:
Paper Submission Deadline: December 2nd, 2018.
Notification of Acceptance: February 8th, 2019.
Camera-ready Due and Early bird registration: April 5th, 2019.

Detailed information on **Submission - Exhibition - Sponsoring - Advertising** at:

HTTP://DTIP-MEMS.ORG/

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